CAT25A256

256-Kb SPI Serial CMOS EEPROM

Description

The CAT25A256 is a 256−Kb Serial CMOS EEPROM device internally organized as 32Kx8 bits. This features a 64−byte page write buffer and supports the Serial Peripheral Interface (SPI) protocol. The device is enabled through a Chip Select ($\overline{CS}$) input. In addition, the required bus signals are clock input (SCK), data input (SI) and data output (SO) lines. The $\overline{HOLD}$ input may be used to pause any serial communication with the CAT25A256 device. The device features software and hardware write protection, including partial as well as full array protection.

Features

- 5 MHz SPI Compatible
- 1.8 V to 5.5 V Supply Voltage Range
- SPI Modes (0,0) & (1,1)
- 64−byte Page Write Buffer
- Self−timed Write Cycle
- Hardware and Software Protection
  – Protect 1/4, 1/2 or Entire EEPROM Array
- Low Power CMOS Technology
- 1,000,000 Program/Erase Cycles
- 100 Year Data Retention
- Die Sales: Wafer Form, Die in Tape & Reel or Wafer Pack
- This Device is Pb−Free, Halogen Free/BFR Free, and RoHS Compliant

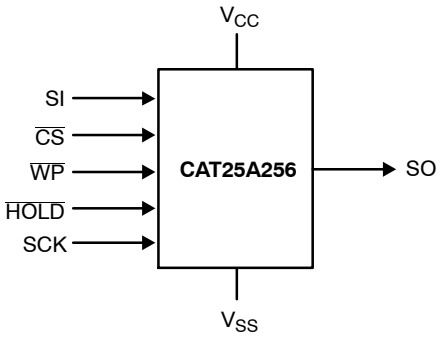

Figure 1. Functional Symbol

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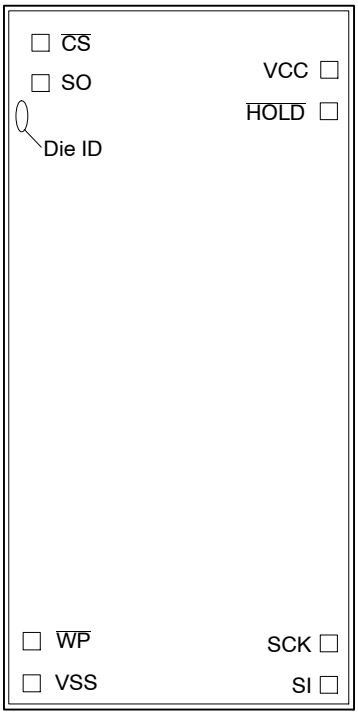
DIE−PAD CONFIGURATION



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PIN FUNCTION

Pad	Pad Name	Function
1	$\overline{CS}$	Chip Select
2	SO	Serial Data Output
3	$\overline{WP}$	Write Protect
4	V_{SS}	Ground
5	SI	Serial Data Input
6	SCK	Serial Clock
7	$\overline{HOLD}$	Hold Transmission Input
8	V_{CC}	Power Supply

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 13 of this data sheet.

Table 1. ABSOLUTE MAXIMUM RATINGS

Parameters	Ratings	Units
Operating Temperature	−40 to +85	°C
Storage Temperature	−65 to +150	°C
Voltage on any Pin with Respect to Ground (Note 1)	−0.5 to +6.5	V

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. The DC input voltage on any pin should not be lower than −0.5 V or higher than V_{CC} + 0.5 V. During transitions, the voltage on any pin may undershoot to no less than −1.5 V or overshoot to no more than V_{CC} + 1.5 V, for periods of less than 20 ns.

Table 2. RELIABILITY CHARACTERISTICS (Note 2)

Symbol	Parameter	Min	Units
N_{END} (Note 3)	Endurance	1,000,000	Program / Erase Cycles
T_{DR}	Data Retention	100	Years

2. These parameters are tested initially and after a design or process change that affects the parameter according to appropriate AEC−Q100 and JEDEC test methods.
3. Page Mode, V_{CC} = 5 V, 25°C.

Table 3. D.C. OPERATING CHARACTERISTICS (V_{CC} = 1.8 V to 5.5 V, T_A = 0°C to +70°C, unless otherwise specified.)

Symbol	Parameter	Test Conditions		Min	Max	Units
I_{CCR}	Supply Current (Read Mode)	V_{CC} = 5.5 V, SO open	5 MHz		550	μA
		V_{CC} = 2.5 V, SO open	5 MHz		400	μA
		V_{CC} = 1.8 V, SO open	3 MHz		300	μA
I_{CCW}	Supply Current (Write Mode)	V_{CC} = 5.5 V, SO open	5 MHz		1.5	mA
		V_{CC} = 2.5 V, SO open	5 MHz		1.25	mA
		V_{CC} = 1.8 V, SO open	3 MHz		1	mA
I_{SB1}	Standby Current	V_{IN} = GND or V_{CC}, $\overline{CS}$ = V_{CC}, $\overline{WP}$ = V_{CC}, $\overline{HOLD}$ = V_{CC}, V_{CC} = 5.5 V			1	μA
I_{SB2}	Standby Current	V_{IN} = GND or V_{CC}, $\overline{CS}$ = V_{CC}, $\overline{WP}$ = GND, $\overline{HOLD}$ = GND, V_{CC} = 5.5 V			4	μA
I_L	Input Leakage Current	V_{IN} = GND or V_{CC}		−2	2	μA
I_{LO}	Output Leakage Current	$\overline{CS}$ = V_{CC}, V_{OUT} = GND or V_{CC}		−1	1	μA
V_{IL}	Input Low Voltage			−0.5	0.3 V_{CC}	V
V_{IH}	Input High Voltage			0.7 V_{CC}	V_{CC} + 0.5	V
V_{OL1}	Output Low Voltage	V_{CC} > 2.5 V, I_{OL} = 3.0 mA			0.4	V
V_{OH1}	Output High Voltage	V_{CC} > 2.5 V, I_{OH} = −1.6 mA		V_{CC} − 0.8 V		V
V_{OL2}	Output Low Voltage	V_{CC} > 1.8 V, I_{OL} = 150 μA			0.2	V
V_{OH2}	Output High Voltage	V_{CC} > 1.8 V, I_{OH} = −100 μA		V_{CC} − 0.2 V		V

Table 4. PIN CAPACITANCE (Note 2) (T_A = 25°C, f = 1.0 MHz, V_{CC} = +5.0 V)

Symbol	Test	Conditions	Min	Typ	Max	Units
C_{OUT}	Output Capacitance (SO)	V_{OUT} = 0 V			8	pF
C_{IN}	Input Capacitance ($\overline{CS}$, SCK, SI, $\overline{WP}$, $\overline{HOLD}$)	V_{IN} = 0 V			8	pF

Table 5. A.C. CHARACTERISTICS (Note 4)

Symbol	Parameter	V_{CC} = 1.8 V – 5.5 V 0°C to +70°C		V_{CC} = 2.5 V – 5.5 V 0°C to +70°C		Units
		Min	Max	Min	Max	
f_{SCK}	Clock Frequency	DC	3	DC	5	MHz
t_{SU}	Data Setup Time	70		35		ns
t_H	Data Hold Time	70		35		ns
t_{WH}	SCK High Time	150		75		ns
t_{WL}	SCK Low Time	150		75		ns
t_{LZ}	$\overline{HOLD}$ to Output Low Z		50		50	ns
t_{RI} (Note 5)	Input Rise Time		2		2	μs
t_{FI} (Note 5)	Input Fall Time		2		2	μs
t_{HD}	$\overline{HOLD}$ Setup Time	0		0		ns
t_{CD}	$\overline{HOLD}$ Hold Time	10		10		ns
t_V	Output Valid from Clock Low		150		75	ns
t_{HO}	Output Hold Time	0		0		ns
t_{DIS}	Output Disable Time		50		50	ns
t_{HZ}	$\overline{HOLD}$ to Output High Z		100		100	ns
t_{CS}	$\overline{CS}$ High Time	150				ns
t_{CSS}	$\overline{CS}$ Setup Time	50		30		ns
t_{CSH}	$\overline{CS}$ Hold Time	50		30		ns
t_{CNS}	$\overline{CS}$ Inactive Setup Time	20		20		ns
t_{CNH}	$\overline{CS}$ Inactive Hold Time	20		20		ns
t_{WPS}	$\overline{WP}$ Setup Time	10		10		ns
t_{WPH}	$\overline{WP}$ Hold Time	100		100		ns
t_{WC} (Note 6)	Write Cycle Time		5		5	ms

4. AC Test Conditions:
   Input Pulse Voltages: 0.3 V_{CC} to 0.7 V_{CC}
   Input rise and fall times: ≤ 10 ns
   Input and output reference voltages: 0.5 V_{CC}
   Output load: current source $I_{OL\ max}/I_{OH\ max}$; C_L = 50 pF

5. This parameter is tested initially and after a design or process change that affects the parameter.

6. t_{WC} is the time from the rising edge of $\overline{CS}$ after a valid write sequence to the end of the internal write cycle.

Table 6. POWER−UP TIMING (Notes 5, 7)

Symbol	Parameter	Max	Units
t_{PUR}	Power−up to Read Operation	1	ms
t_{PUW}	Power−up to Write Operation	1	ms

7. t_{PUR} and t_{PUW} are the delays required from the time V_{CC} is stable until the specified operation can be initiated.

Pin Description

SI: The serial data input pin accepts op−codes, addresses and data. In SPI modes (0,0) and (1,1) input data is latched on the rising edge of the SCK clock input.

SO: The serial data output pin is used to transfer data out of the device. In SPI modes (0,0) and (1,1) data is shifted out on the falling edge of the SCK clock.

SCK: The serial clock input pin accepts the clock provided by the host and used for synchronizing communication between host and CAT25A256.

$\overline{CS}$: The chip select input pin is used to enable/disable the CAT25A256. When $\overline{CS}$ is high, the SO output is tri−stated (high impedance) and the device is in Standby Mode (unless an internal write operation is in progress). *Every communication session between host and CAT25A256 must be preceded by a high to low transition and concluded with a low to high transition of the $\overline{CS}$ input.*

$\overline{WP}$: The write protect input pin will allow all write operations to the device when held high. When $\overline{WP}$ pin is tied low and the WPEN bit in the Status Register (refer to Status Register description, later in this Data Sheet) is set to "1", writing to the Status Register is disabled.

$\overline{HOLD}$: The $\overline{HOLD}$ input pin is used to pause transmission between host and CAT25A256, without having to retransmit the entire sequence at a later time. To pause, $\overline{HOLD}$ must be taken low and to resume it must be taken back high, with the SCK input low during both transitions. When not used for pausing, it is recommended the $\overline{HOLD}$ input to be tied to V_{CC}, either directly or through a resistor.

Functional Description

The CAT25A256 device supports the Serial Peripheral Interface (SPI) bus protocol, modes (0,0) and (1,1). The device contains an 8−bit instruction register. The instruction set and associated op−codes are listed in Table 7.

Reading data stored in the CAT25A256 is accomplished by simply providing the READ command and an address. Writing to the CAT25A256, in addition to a WRITE command, address and data, also requires enabling the device for writing by first setting certain bits in a Status Register, as will be explained later.

After a high to low transition on the $\overline{CS}$ input pin, the CAT25A256 will accept any one of the six instruction op−codes listed in Table 7 and will ignore all other possible 8−bit combinations. The communication protocol follows the timing from Figure 2.

Table 7. INSTRUCTION SET

Instruction	Opcode	Operation
WREN	0000 0110	Enable Write Operations
WRDI	0000 0100	Disable Write Operations
RDSR	0000 0101	Read Status Register
WRSR	0000 0001	Write Status Register
READ	0000 0011	Read Data from Memory
WRITE	0000 0010	Write Data to Memory

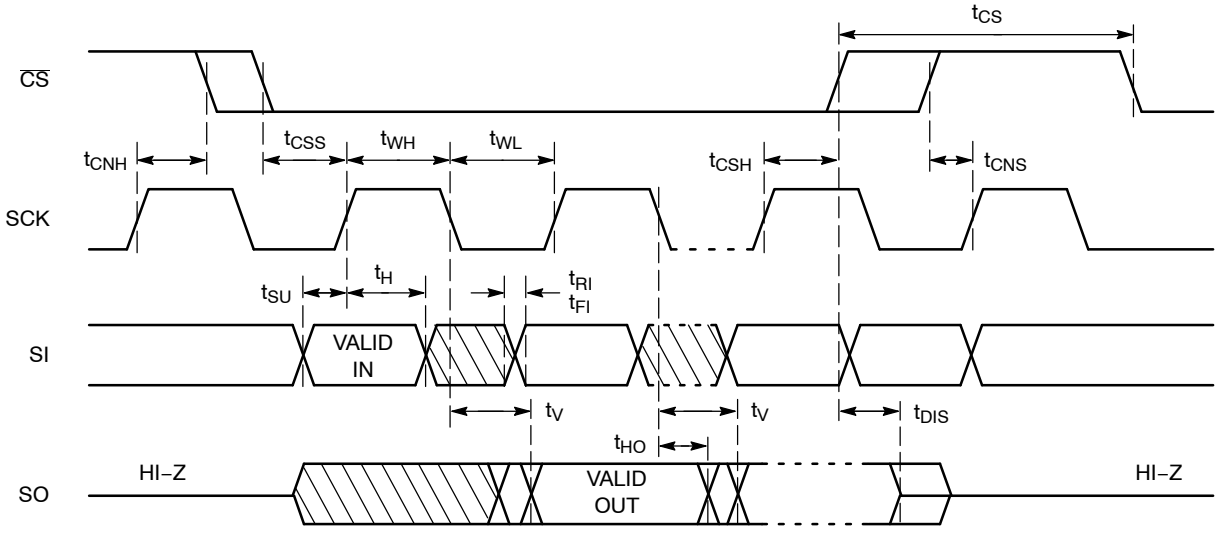


Figure 2. Synchronous Data Timing

Status Register

The Status Register, as shown in Table 8, contains a number of status and control bits.

The $\overline{\text{RDY}}$ (Ready) bit indicates whether the device is busy with a write operation. This bit is automatically set to 1 during an internal write cycle, and reset to 0 when the device is ready to accept commands. For the host, this bit is read only.

The WEL (Write Enable Latch) bit is set/reset by the WREN/WRDI commands. When set to 1, the device is in a Write Enable state and when set to 0, the device is in a Write Disable state.

The BP0 and BP1 (Block Protect) bits determine which blocks are currently write protected. They are set by the user with the WRSR command and are non−volatile. The user is allowed to protect a quarter, one half or the entire memory, by setting these bits according to Table 9. The protected blocks then become read−only.

The WPEN (Write Protect Enable) bit acts as an enable for the $\overline{\text{WP}}$ pin. Hardware write protection is enabled when the $\overline{\text{WP}}$ pin is low and the WPEN bit is 1. This condition prevents writing to the status register and to the block protected sections of memory. While hardware write protection is active, only the non−block protected memory can be written. Hardware write protection is disabled when the $\overline{\text{WP}}$ pin is high or the WPEN bit is 0. The WPEN bit, $\overline{\text{WP}}$ pin and WEL bit combine to either permit or inhibit Write operations, as detailed in Table 10.

Table 8. STATUS REGISTER

7	6	5	4	3	2	1	0
WPEN	0	0	0	BP1	BP0	WEL	$\overline{\text{RDY}}$

Table 9. BLOCK PROTECTION BITS

Status Register Bits		Array Address Protected	Protection
BP1	BP0		
0	0	None	No Protection
0	1	6000−7FFF	Quarter Array Protection
1	0	4000−7FFF	Half Array Protection
1	1	0000−7FFF	Full Array Protection

Table 10. WRITE PROTECT CONDITIONS

WPEN	$\overline{\text{WP}}$	WEL	Protected Blocks	Unprotected Blocks	Status Register
0	X	0	Protected	Protected	Protected
0	X	1	Protected	Writable	Writable
1	Low	0	Protected	Protected	Protected
1	Low	1	Protected	Writable	Protected
X	High	0	Protected	Protected	Protected
X	High	1	Protected	Writable	Writable

WRITE OPERATIONS

The CAT25A256 device powers up into a write disable state. The device contains a Write Enable Latch (WEL) which must be set before attempting to write to the memory array or to the status register. In addition, the address of the memory location(s) to be written must be outside the protected area, as defined by BP0 and BP1 bits from the status register.

Write Enable and Write Disable

The internal Write Enable Latch and the corresponding Status Register WEL bit are set by sending the WREN instruction to the CAT25A256. Care must be taken to take the $\overline{CS}$ input high after the WREN instruction, as otherwise the Write Enable Latch will not be properly set. WREN timing is illustrated in Figure 3. The WREN instruction must be sent prior to any WRITE or WRSR instruction.

The internal write enable latch is reset by sending the WRDI instruction as shown in Figure 4. Disabling write operations by resetting the WEL bit, will protect the device against inadvertent writes.

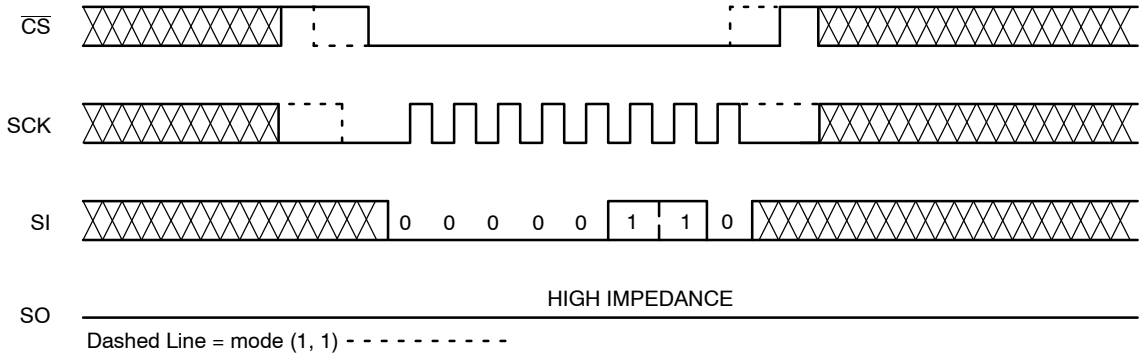


Figure 3. WREN Timing

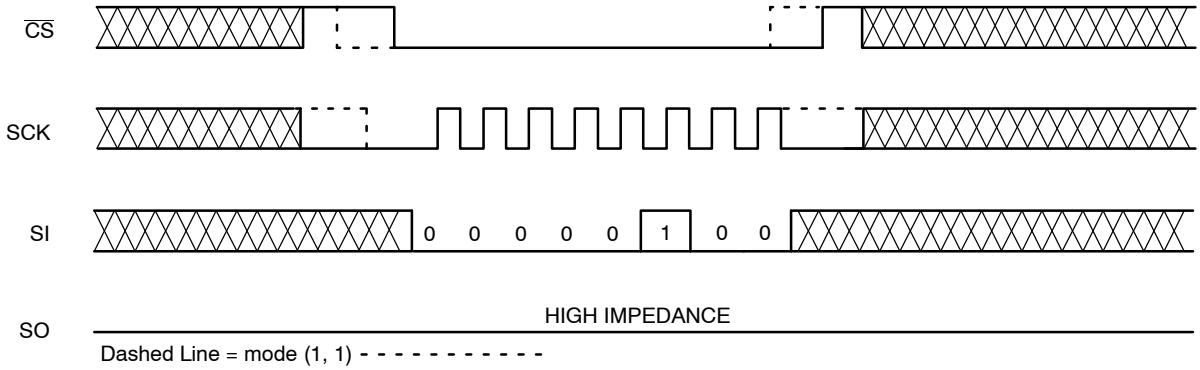


Figure 4. WRDI Timing

Byte Write

Once the WEL bit is set, the user may execute a write sequence, by sending a WRITE instruction, a 16−bit address and data as shown in Figure 5. Only 15 significant address bits are used by the CAT25A256. The 16th address bit is don't care, as shown in Table 11. Internal programming will start after the low to high $\overline{CS}$ transition. During an internal write cycle, all commands, except for RDSR (Read Status Register) will be ignored. The $\overline{RDY}$ bit will indicate if the internal write cycle is in progress ($\overline{RDY}$ high), or the device is ready to accept commands ($\overline{RDY}$ low).

Page Write

After sending the first data byte to the CAT25A256, the host may continue sending data, up to a total of 64 bytes, according to timing shown in Figure 6. After each data byte, the lower order address bits are automatically incremented, while the higher order address bits (page address) remain unchanged. If during this process the end of page is exceeded, then loading will "roll over" to the first byte in the page, thus possibly overwriting previously loaded data. Following completion of the write cycle, the CAT25A256 is automatically returned to the write disable state. While the internal write cycle is in progress, the RDSR command will output the $\overline{RDY}$ (Ready) bit status only (i.e., data out = FFh).

Table 11. BYTE ADDRESS

Device	Address Significant Bits	Address Don't Care Bits	# Address Clock Pulses
CAT25A256	A14 – A0	A15	16

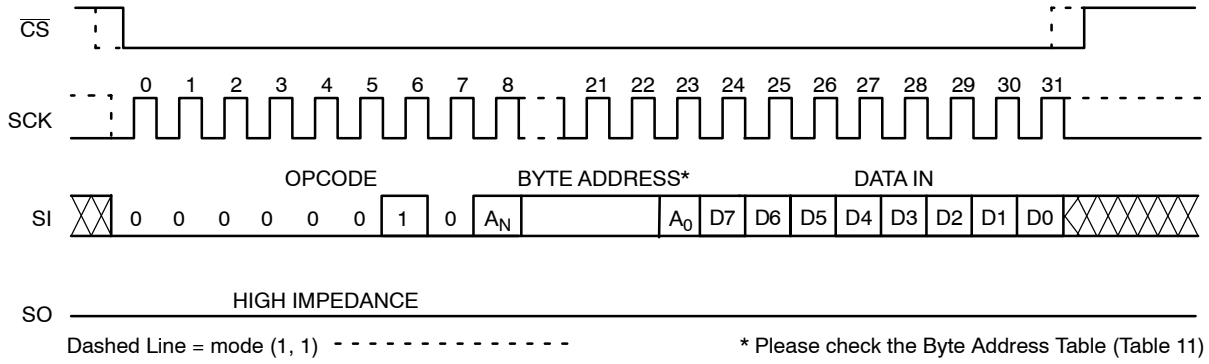


Figure 5. Byte WRITE Timing

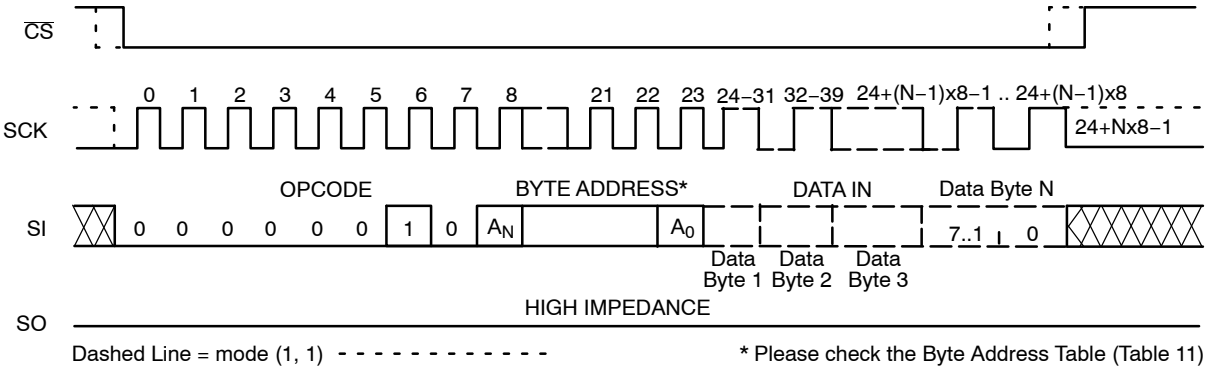


Figure 6. Page WRITE Timing

Write Status Register

The Status Register is written by sending a WRSR instruction according to timing shown in Figure 7. Only bits 2, 3 and 7 can be written using the WRSR command.

Write Protection

The Write Protect ($\overline{WP}$) pin can be used to protect the Block Protect bits BP0 and BP1 against being inadvertently altered. When $\overline{WP}$ is low and the WPEN bit is set to “1”, write operations to the Status Register are inhibited. $\overline{WP}$ going low while $\overline{CS}$ is still low will interrupt a write to the status register. If the internal write cycle has already been initiated, $\overline{WP}$ going low will have no effect on any write operation to the Status Register. The $\overline{WP}$ pin function is blocked when the WPEN bit is set to “0”. The $\overline{WP}$ input timing is shown in Figure 8.

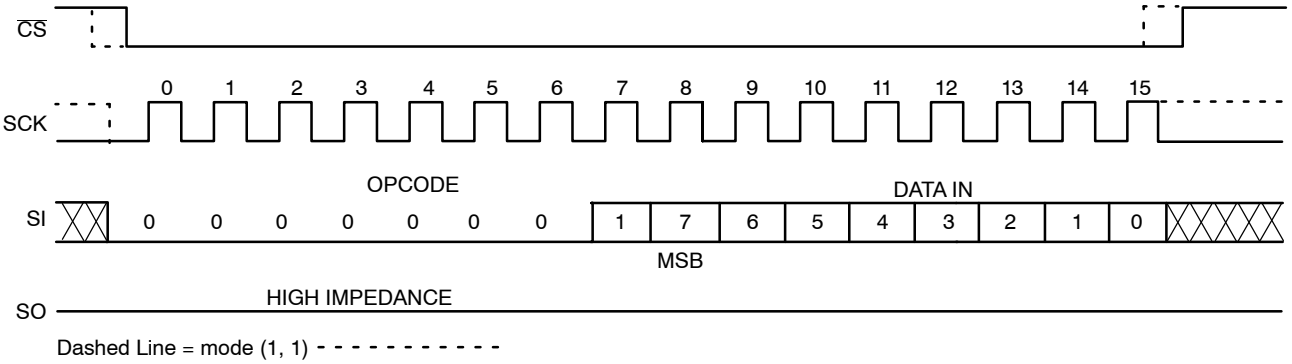


Figure 7. WRSR Timing

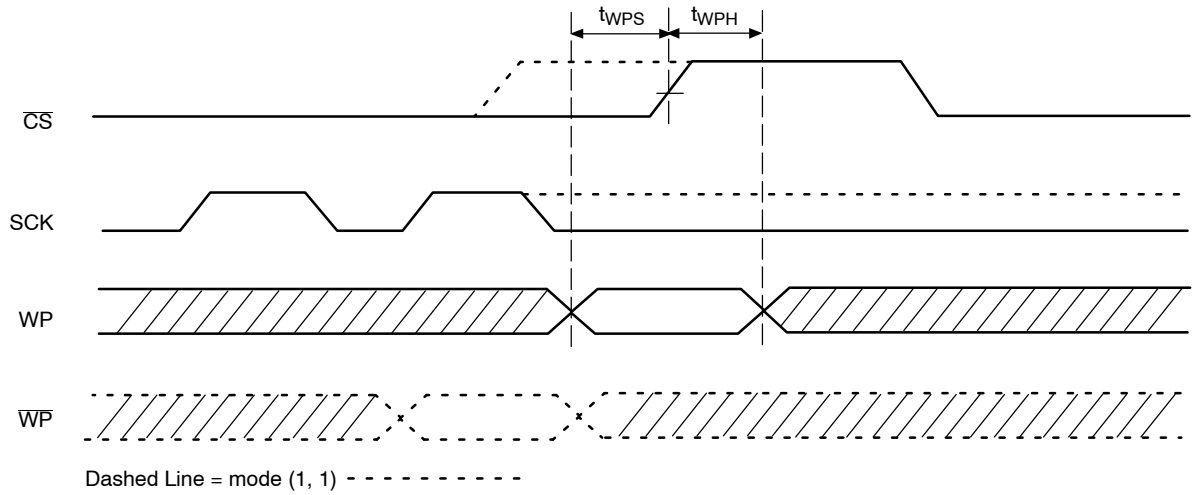


Figure 8. $\overline{WP}$ Timing

READ OPERATIONS

Read from Memory Array

To read from memory, the host sends a READ instruction followed by a 16−bit address (see Table 11 for the number of significant address bits).

After receiving the last address bit, the CAT25A256 will respond by shifting out data on the SO pin (as shown in Figure 9). Sequentially stored data can be read out by simply continuing to run the clock. The internal address pointer is automatically incremented to the next higher address as data is shifted out. After reaching the highest memory address, the address counter "rolls over" to the lowest memory address, and the read cycle can be continued indefinitely. The read operation is terminated by taking $\overline{CS}$ high.

Read Status Register

To read the status register, the host simply sends a RDSR command. After receiving the last bit of the command, the CAT25A256 will shift out the contents of the status register on the SO pin (Figure 10). The status register may be read at any time, including during an internal write cycle. While the internal write cycle is in progress, the RDSR command will output the $\overline{RDY}$ (Ready) bit status only (i.e., data out = FFh).

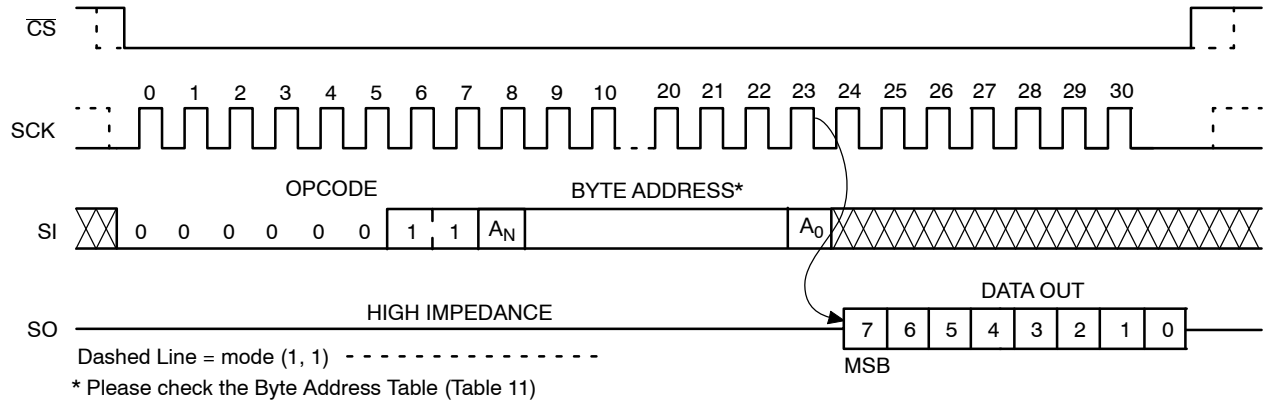


Figure 9. READ Timing

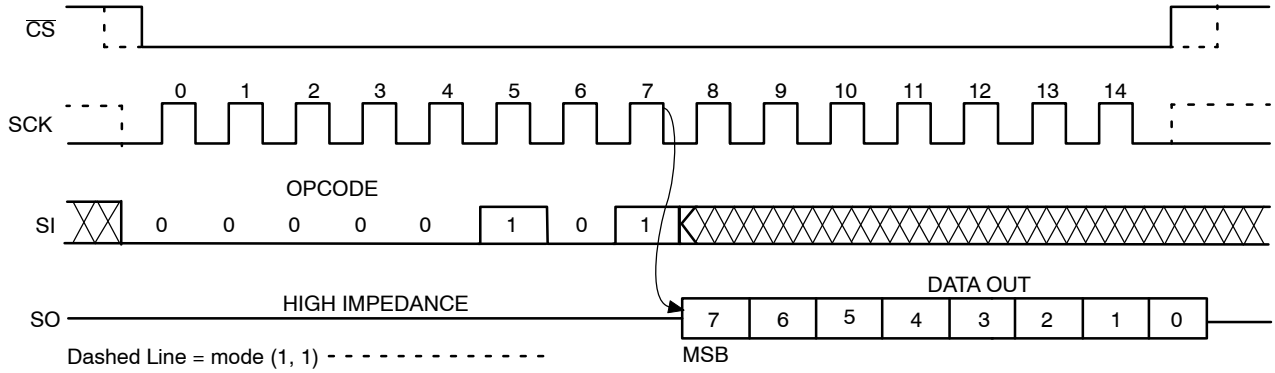


Figure 10. RDSR Timing

Hold Operation

The $\overline{\text{HOLD}}$ input can be used to pause communication between host and CAT25A256. To pause, $\overline{\text{HOLD}}$ must be taken low while SCK is low (Figure 11). During the hold condition the device must remain selected ($\overline{\text{CS}}$ low). During the pause, the data output pin (SO) is tri−stated (high impedance) and SI transitions are ignored. To resume communication, $\overline{\text{HOLD}}$ must be taken high while SCK is low.

Design Considerations

The CAT25A256 device incorporates Power−On Reset (POR) circuitry which protects the internal logic against powering up in the wrong state. The device will power up into Standby mode after V_{CC} exceeds the POR trigger level and will power down into Reset mode when V_{CC} drops below the POR trigger level. This bi−directional POR behavior protects the device against ‘brown−out’ failure following a temporary loss of power.

The CAT25A256 device powers up in a write disable state and in a low power standby mode. A WREN instruction must be issued prior to any writes to the device.

After power up, the $\overline{\text{CS}}$ pin must be brought low to enter a ready state and receive an instruction. After a successful byte/page write or status register write, the device goes into a write disable mode. The $\overline{\text{CS}}$ input must be set high after the proper number of clock cycles to start the internal write cycle. Access to the memory array during an internal write cycle is ignored and programming is continued. Any invalid op−code will be ignored and the serial output pin (SO) will remain in the high impedance state.

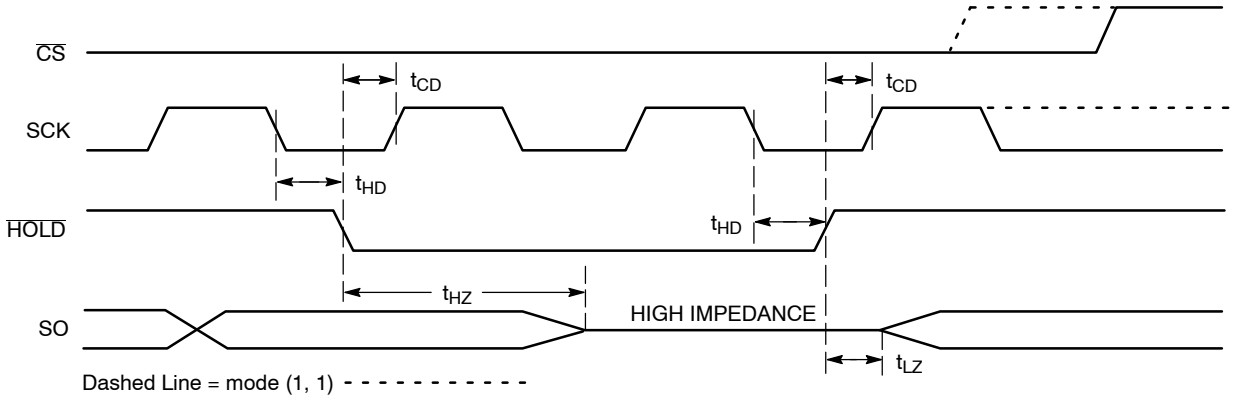
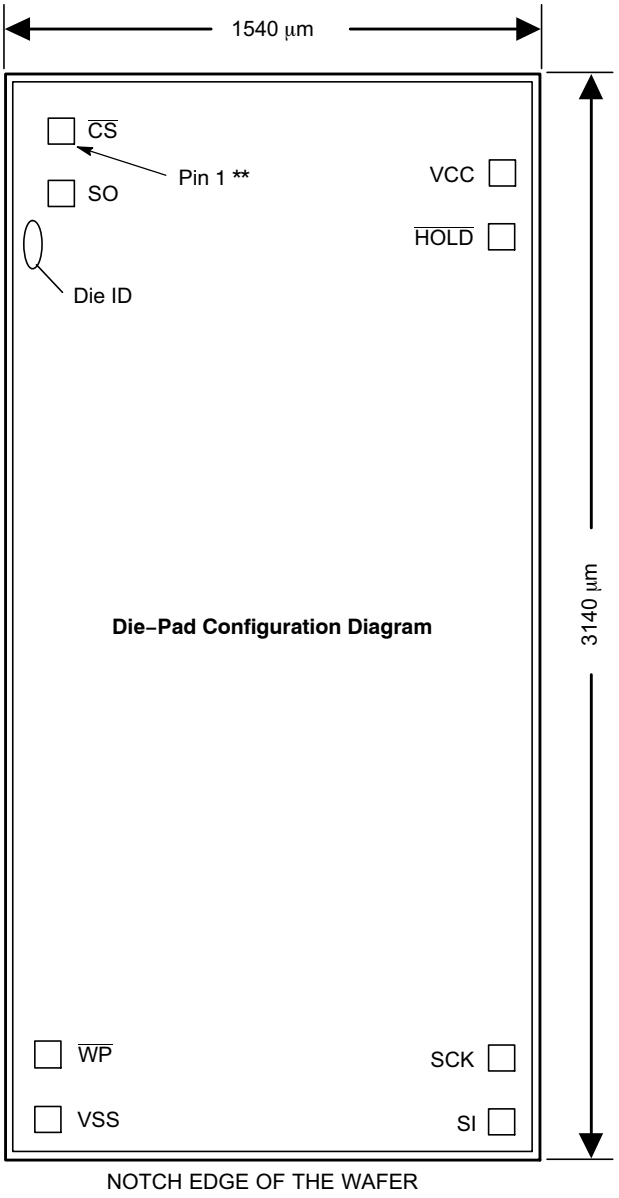


Figure 11. $\overline{\text{HOLD}}$ Timing

Die Size and Pad Location



Die−Pad Configuration Diagram

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Pad Location*

Pad	Pad Name	X	Y	Unit
1	$\overline{CS}$	−616.65	1411.4	μm
2	SO	−616.65	1228.75	μm
3	$\overline{WP}$	−658.6	−1274.7	μm
4	VSS	−658.6	−1461.3	μm
5	SI	667.4	−1469.25	μm
6	SCK	667.4	−1282.65	μm
7	$\overline{HOLD}$	667.4	1105.25	μm
8	VCC	667.4	1291.85	μm

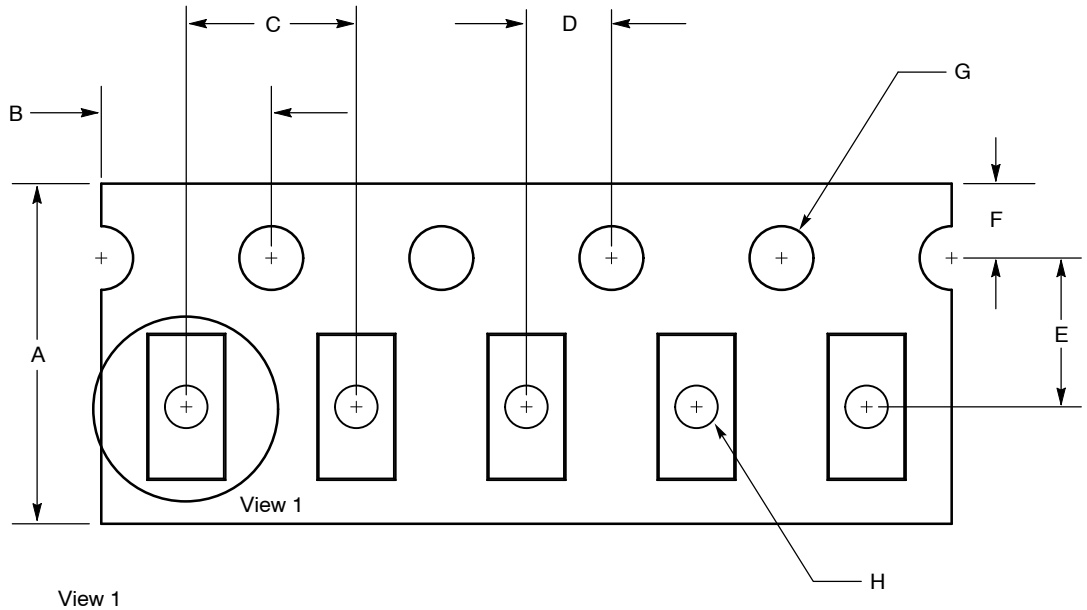
* Pads location coordinates relative to the origin at the center of the die.

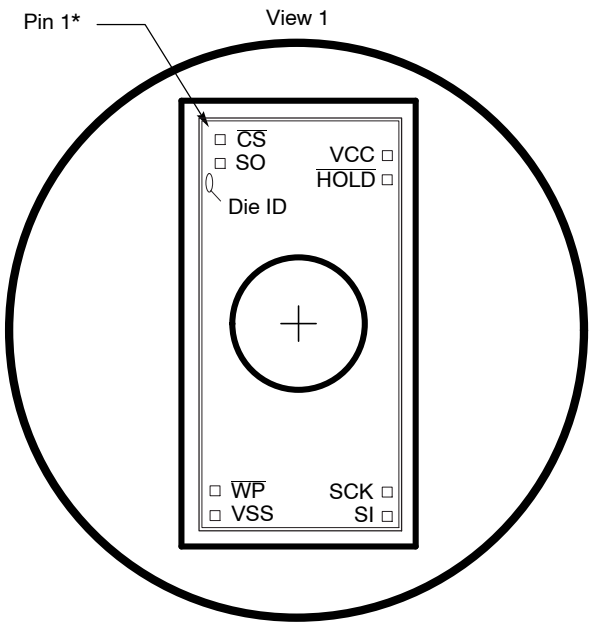
** Pin 1 is for die orientation in Tape and Reel.

Die Mechanical Dimensions

Specification	Min	Typ	Max	Unit
Bond pad opening	− −	80 x 80 3.149 x 3.149	− −	μm mils
Bond pad spacing	102 4.015	106 4.173	− −	μm mils
Die thickness	330.2 13	355.6 14	381 15	μm mils
Custom die thickness	279.4 11	− −	660.4 26	μm mils
Die thickness tolerance	− −	12.7 0.5	25.4 1	μm mils
Die size before saw−cut (wafer stepping)	− −	1590 x 3190 62.598 x 125.59	− −	μm mils
Die size after saw−cut	− −	1540 x 3140 60.629 x 123.622	− −	μm mils

Tape and Reel Specifications

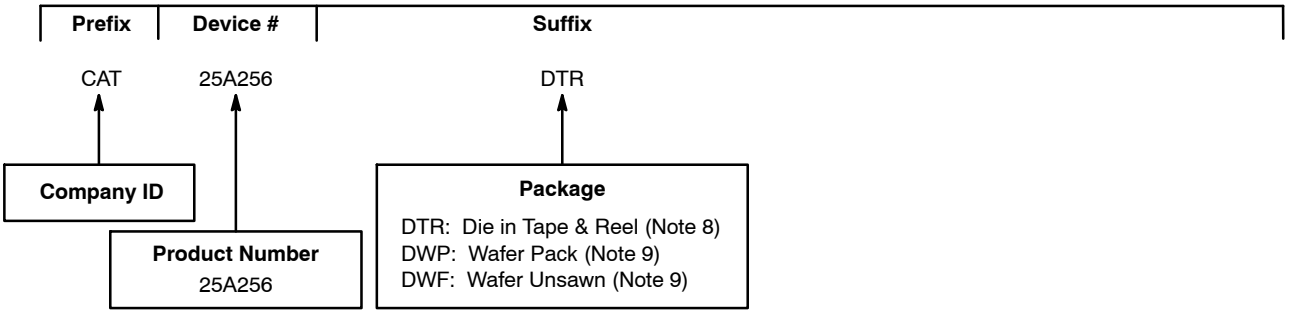




SYMBOL	MIN	NOM	MAX
A	7.90	8.00	8.30
B	3.90	4.00	4.10
C	3.90	4.00	4.10
D	1.95	2.00	2.05
E	3.45	3.50	3.55
F	1.65	1.75	1.85
G		1.50	1.60
H		1.00	1.25

*Pin 1 is for die orientation in Tape and Reel

Example of Ordering Information



8. Die available in Tape & Reel, 3,000 pcs/reel: die thickness = 11 mil ± 1 mil.
9. For additional information, contact factory.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:
Literature Distribution Center for ON Semiconductor
P.O. Box 5163, Denver, Colorado 80217 USA
Phone: 303−675−2175 or 800−344−3860 Toll Free USA/Canada
Fax: 303−675−2176 or 800−344−3867 Toll Free USA/Canada
Email: orderlit@onsemi.com

N. American Technical Support: 800−282−9855 Toll Free USA/Canada
Europe, Middle East and Africa Technical Support:
Phone: 421 33 790 2910
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